

Advanced Power MOSFET

IRLZ24A

FEATURES

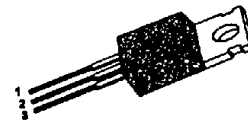
- Logic-Level Gate Drive
- Avalanche Rugged Technology
- Rugged Gate Oxide Technology
- Lower Input Capacitance
- Improved Gate Charge
- Extended Safe Operating Area
- Lower Leakage Current : 10 μ A (Max.) @ $V_{DS} = 60V$
- Lower $R_{DS(ON)}$: 0.061 Ω (Typ.)

$$BV_{DSS} = 60 V$$

$$R_{DS(on)} = 0.075 \Omega$$

$$I_D = 17 A$$

TO-220



1. Gate 2. Drain 3. Source

Absolute Maximum Ratings

| Symbol | Characteristic | Value | Units |
|----------------|---|--------------|------------|
| V_{DSS} | Drain-to-Source Voltage | 60 | V |
| I_D | Continuous Drain Current ($T_C=25^\circ C$) | 17 | A |
| | Continuous Drain Current ($T_C=100^\circ C$) | 12 | |
| I_{DM} | Drain Current-Pulsed | 60 | A |
| V_{GS} | Gate-to-Source Voltage | ± 0 | V |
| E_{AS} | Single Pulsed Avalanche Energy | 149 | mJ |
| I_{AR} | Avalanche Current | 17 | A |
| E_{AR} | Repetitive Avalanche Energy | 4.5 | mJ |
| dv/dt | Peak Diode Recovery dv/dt | 5.5 | V/ns |
| P_D | Total Power Dissipation ($T_C=25^\circ C$) | 45 | W |
| | Linear Derating Factor | 0.3 | |
| T_J, T_{STG} | Operating Junction and Storage Temperature Range | - 55 to +175 | $^\circ C$ |
| T_L | Maximum Lead Temp. for Soldering Purposes, 1/8" from case for 5-seconds | 300 | |

Thermal Resistance

| Symbol | Characteristic | Typ. | Max. | Units |
|-----------------|---------------------|------|------|--------------|
| $R_{\theta JC}$ | Junction-to-Case | -- | 3.3 | $^\circ C/W$ |
| $R_{\theta CS}$ | Case-to-Sink | 0.5 | -- | |
| $R_{\theta JA}$ | Junction-to-Ambient | -- | 62.5 | |

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| Symbol | Characteristic | Min. | Typ. | Max. | Units | Test Condition |
|------------------------|---|------|-------|-------|-----------|---|
| BV_{DSS} | Drain-Source Breakdown Voltage | 60 | -- | -- | V | $V_{GS}=0V, I_D=250\mu A$ |
| $\Delta BV/\Delta T_J$ | Breakdown Voltage Temp. Coeff. | -- | 0.056 | -- | V/°C | $I_D=250\mu A$ See Fig 7 |
| $V_{GS(th)}$ | Gate Threshold Voltage | 1.0 | -- | 2.0 | V | $V_{DS}=5V, I_D=250\mu A$ |
| I_{GSS} | Gate-Source Leakage, Forward | -- | -- | 100 | nA | $V_{GS}=20V$ |
| | Gate-Source Leakage, Reverse | -- | -- | -100 | | $V_{GS}=-20V$ |
| I_{DSS} | Drain-to-Source Leakage Current | -- | -- | 10 | μA | $V_{DS}=60V$ |
| | | -- | -- | 100 | | $V_{DS}=48V, T_C=150^\circ C$ |
| $R_{DS(on)}$ | Static Drain-Source On-State Resistance | -- | -- | 0.075 | Ω | $V_{GS}=5V, I_D=8.5A$ ④ |
| g_{fs} | Forward Transconductance | -- | 9.7 | -- | \bar{v} | $V_{DS}=30V, I_D=8.5A$ ④ |
| C_{iss} | Input Capacitance | -- | 560 | 730 | pF | $V_{GS}=0V, V_{DS}=25V, f=1MHz$ See Fig 5 |
| C_{oss} | Output Capacitance | -- | 195 | 225 | | |
| C_{rss} | Reverse Transfer Capacitance | -- | 77 | 90 | | |
| $t_{d(on)}$ | Turn-On Delay Time | -- | 12 | 35 | ns | $V_{DD}=30V, I_D=17A,$ $R_G=9\Omega$ See Fig 13 ④ ⑤ |
| t_r | Rise Time | -- | 21 | 55 | | |
| $t_{d(off)}$ | Turn-Off Delay Time | -- | 32 | 75 | | |
| t_f | Fall Time | -- | 21 | 55 | | |
| Q_g | Total Gate Charge | -- | 15 | 20 | nC | $V_{DS}=48V, V_{GS}=5V,$ $I_D=17A$ See Fig 6 & Fig 12 ④ ⑤ |
| Q_{gs} | Gate-Source Charge | -- | 4.4 | -- | | |
| Q_{gd} | Gate-Drain("Miller") Charge | -- | 7.3 | -- | | |

Source-Drain Diode Ratings and Characteristics

| Symbol | Characteristic | Min. | Typ. | Max. | Units | Test Condition |
|----------|---------------------------|------|-------|------|---------|---|
| I_S | Continuous Source Current | -- | -- | 17 | A | Integral reverse pn-diode in the MOSFET |
| I_{SM} | Pulsed-Source Current ① | -- | -- | 60 | | |
| V_{SD} | Diode Forward Voltage ④ | -- | -- | 1.5 | V | $T_J=25^\circ C, I_S=17A, V_{GS}=0V$ |
| t_{rr} | Reverse Recovery Time | -- | 55 | -- | ns | $T_J=25^\circ C, I_F=17A$ |
| Q_{rr} | Reverse Recovery Charge | -- | 0.091 | -- | μC | $di_F/dt=100A/\mu s$ ④ |

Notes :

- ① Repetitive Rating : Pulse Width Limited by Maximum Junction Temperature
- ② $L=0.6mH, I_{AS}=17A, V_{DO}=25V, R_G=27\Omega$, Starting $T_J=25^\circ C$
- ③ $I_{SD} \leq 17A, di/dt \leq 250A/\mu s, V_{DO} \leq BV_{DSS}$, Starting $T_J=25^\circ C$
- ④ Pulse Test : Pulse Width = 250 μs , Duty Cycle $\leq 2\%$
- ⑤ Essentially Independent of Operating Temperature

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Fig 1. Output Characteristics

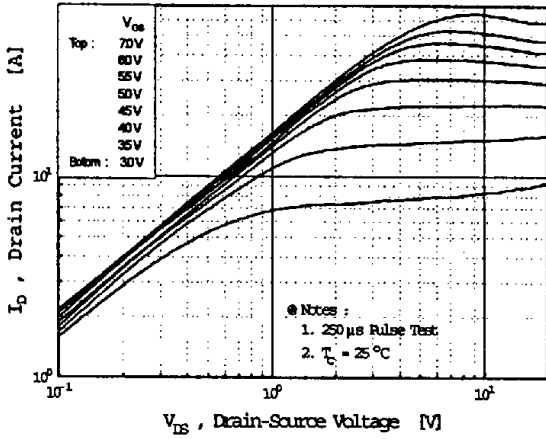


Fig 2. Transfer Characteristics

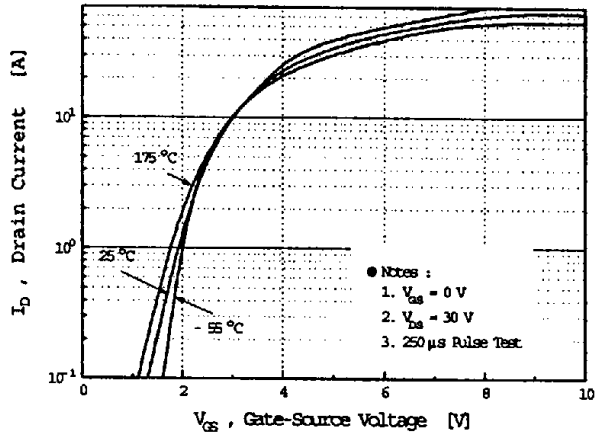


Fig 3. On-Resistance vs. Drain Current

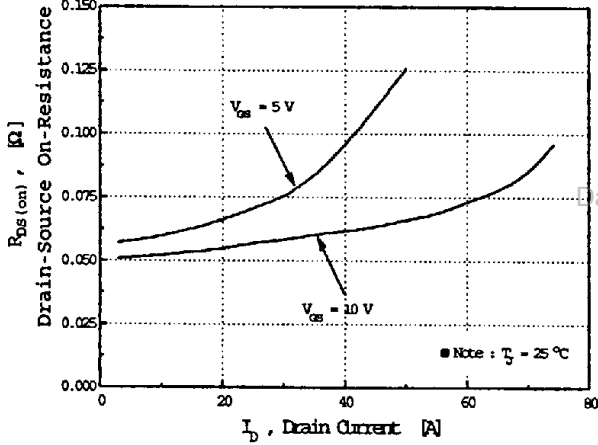


Fig 4. Source-Drain Diode Forward Voltage

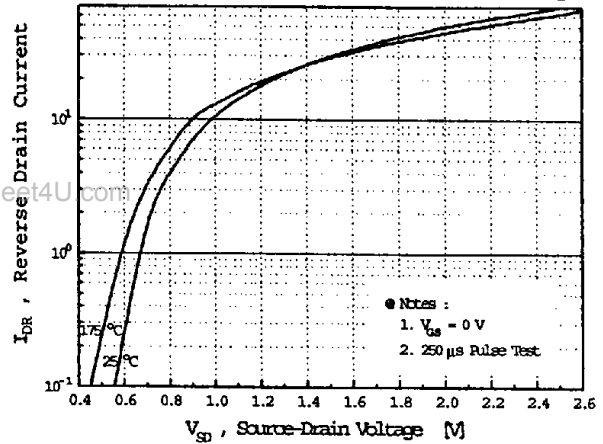


Fig 5. Capacitance vs. Drain-Source Voltage

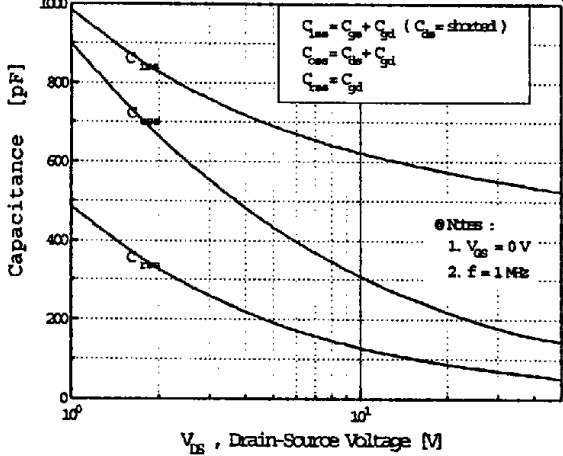
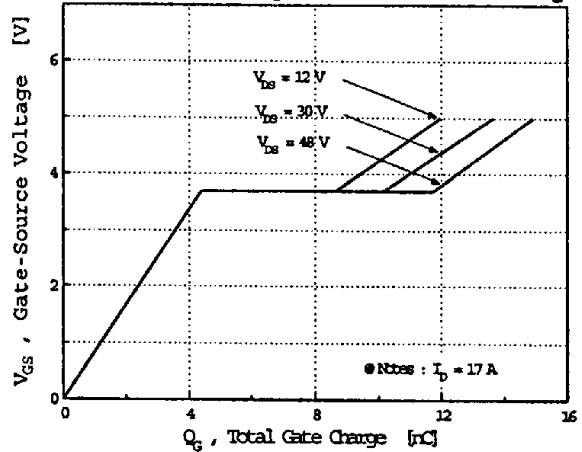


Fig 6. Gate Charge vs. Gate-Source Voltage



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Fig 7. Breakdown Voltage vs. Temperature

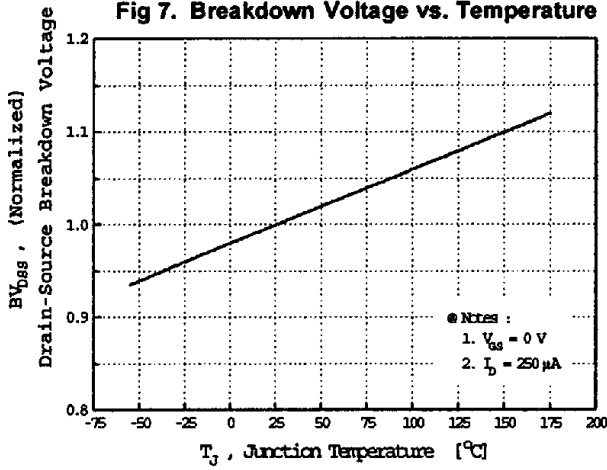


Fig 8. On-Resistance vs. Temperature

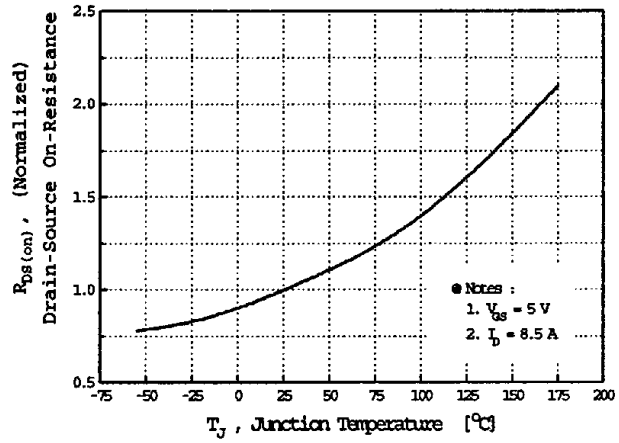


Fig 9. Max. Safe Operating Area

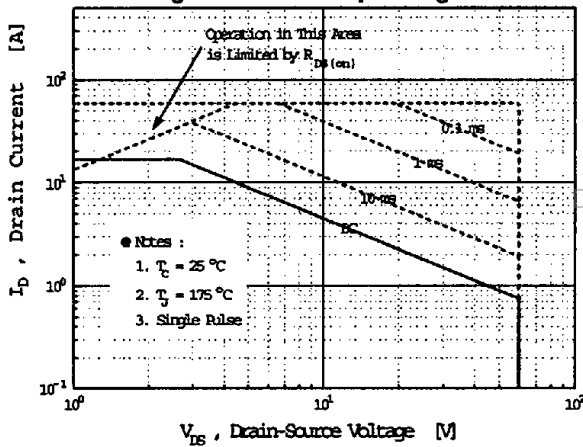


Fig 10. Max. Drain Current vs. Case Temperature

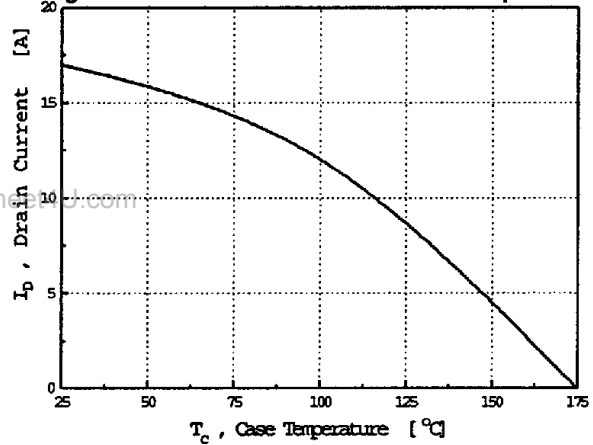
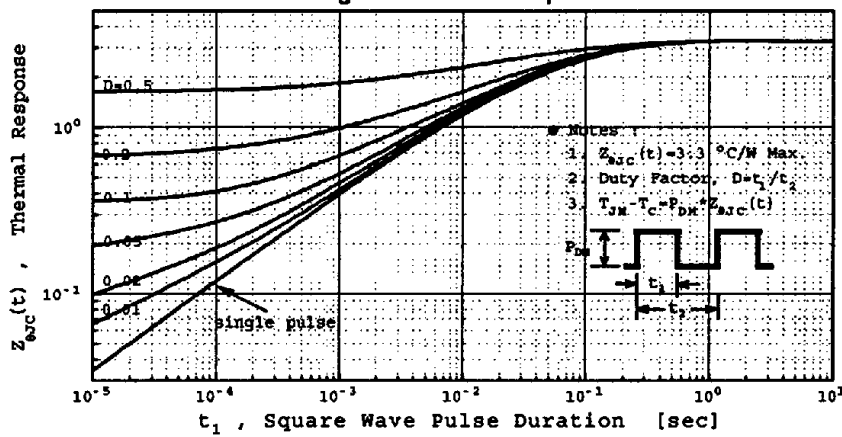


Fig 11. Thermal Response



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Fig 12. Gate Charge Test Circuit & Waveform

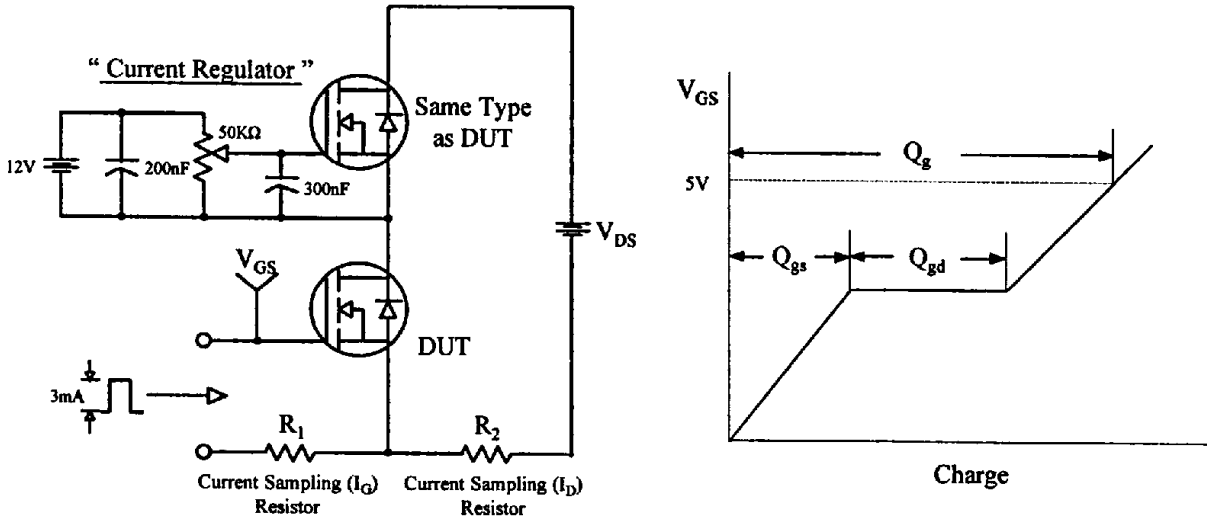


Fig 13. Resistive Switching Test Circuit & Waveforms

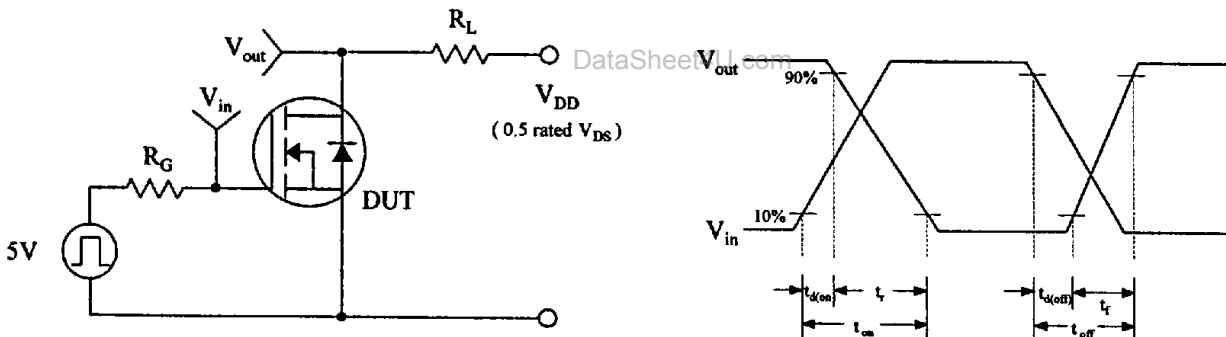
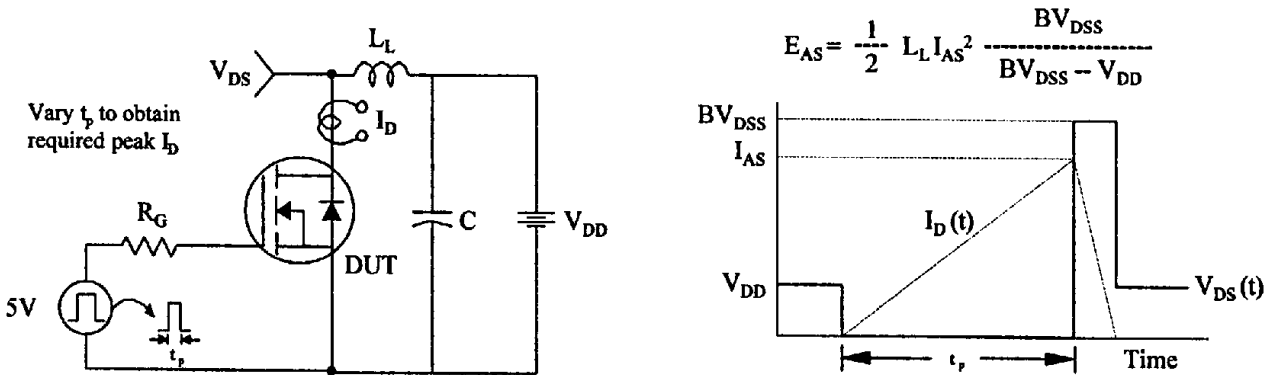


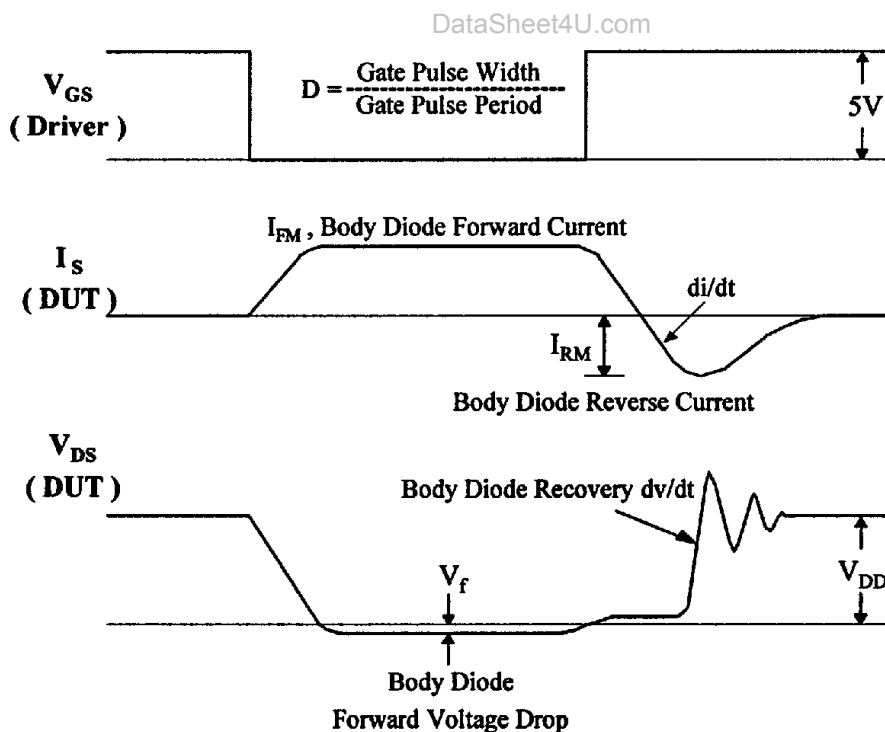
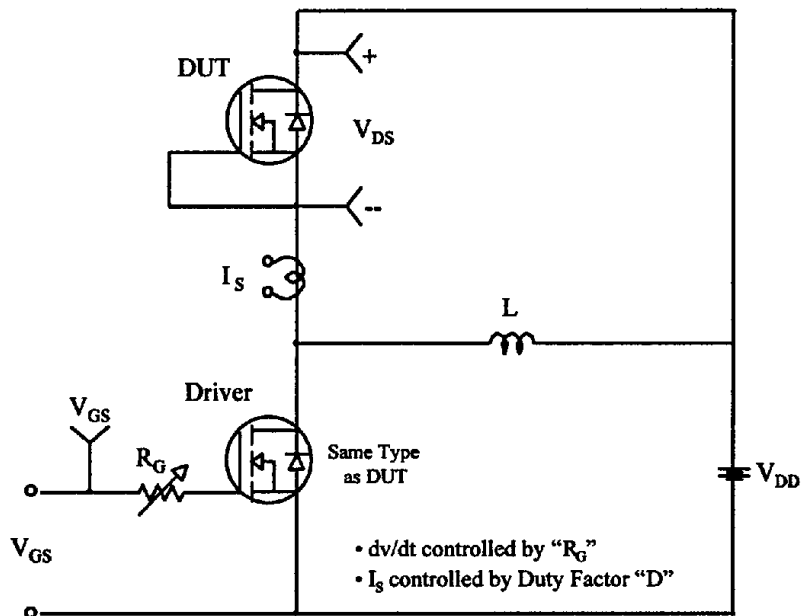
Fig 14. Unclamped Inductive Switching Test Circuit & Waveforms



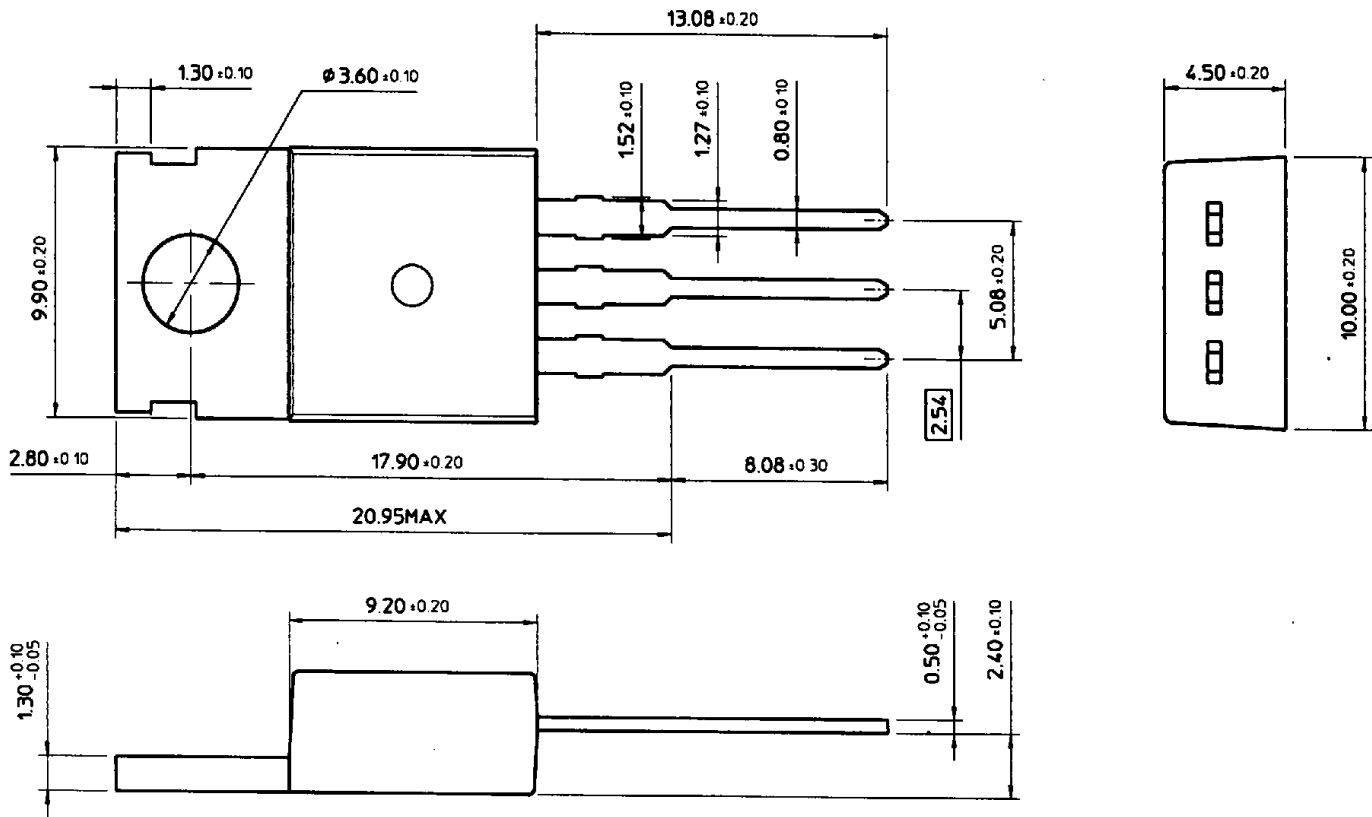
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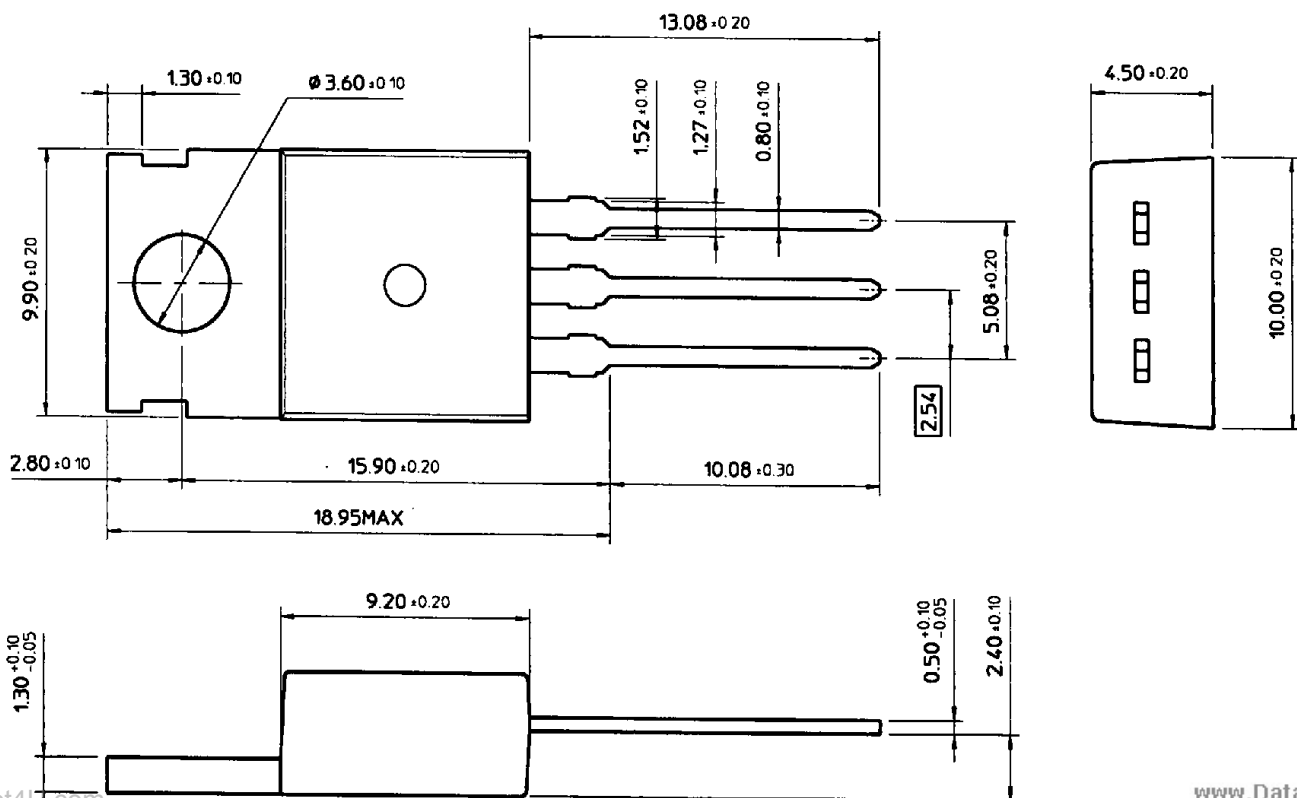
Fig 15. Peak Diode Recovery dv/dt Test Circuit & Waveforms



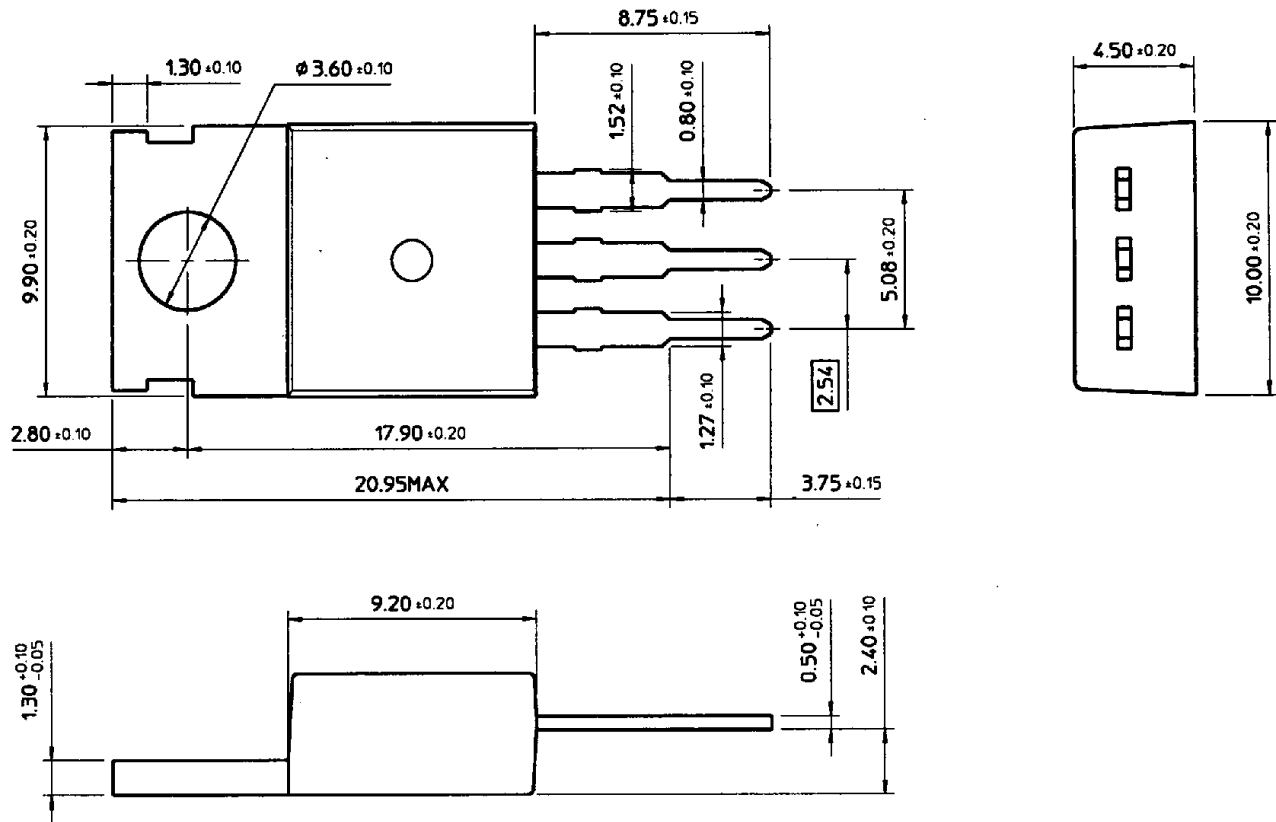
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0-220 (2)



TO-220 (3)

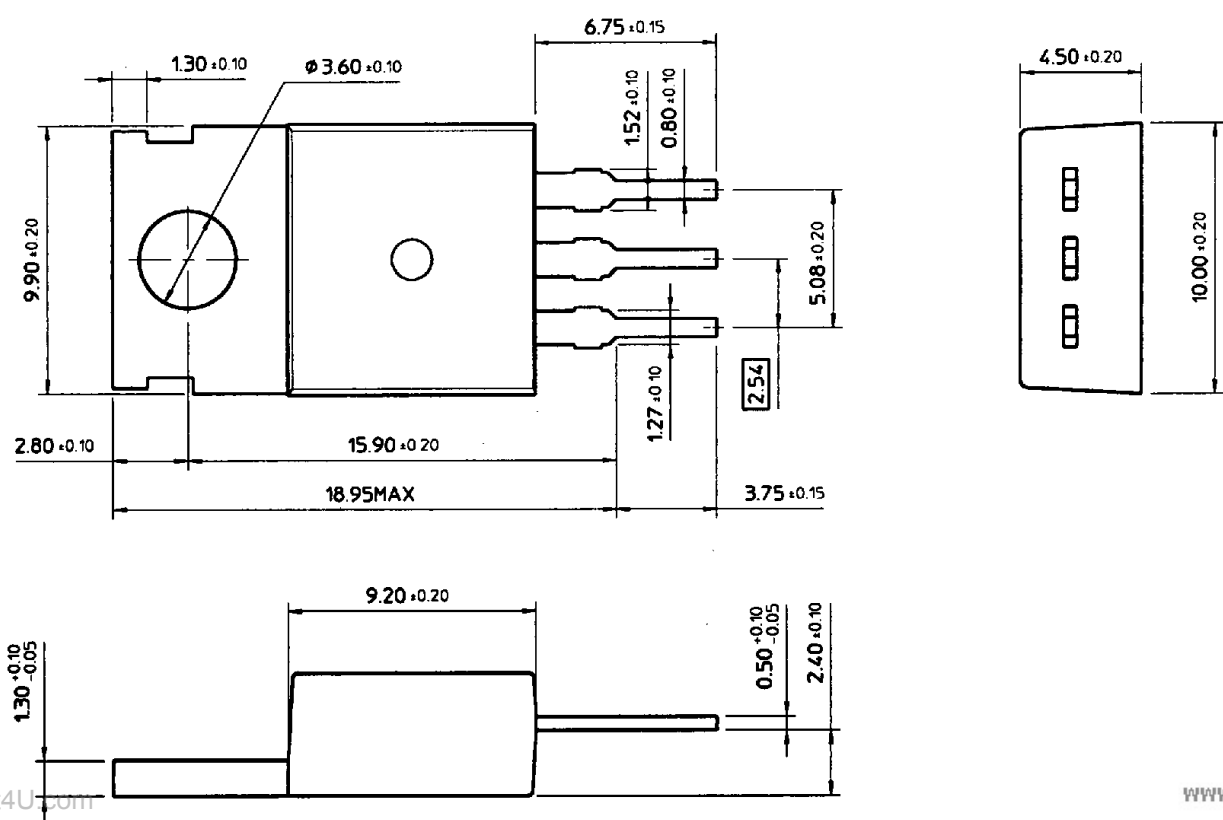


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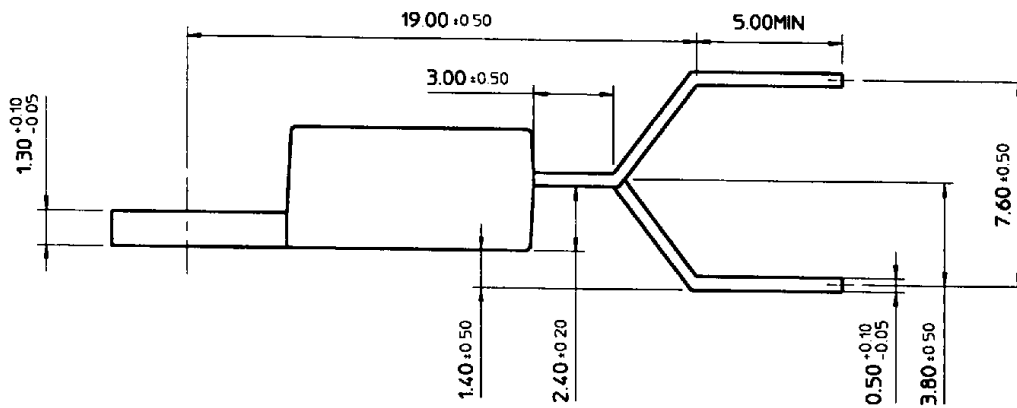
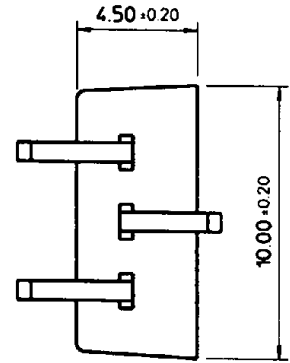
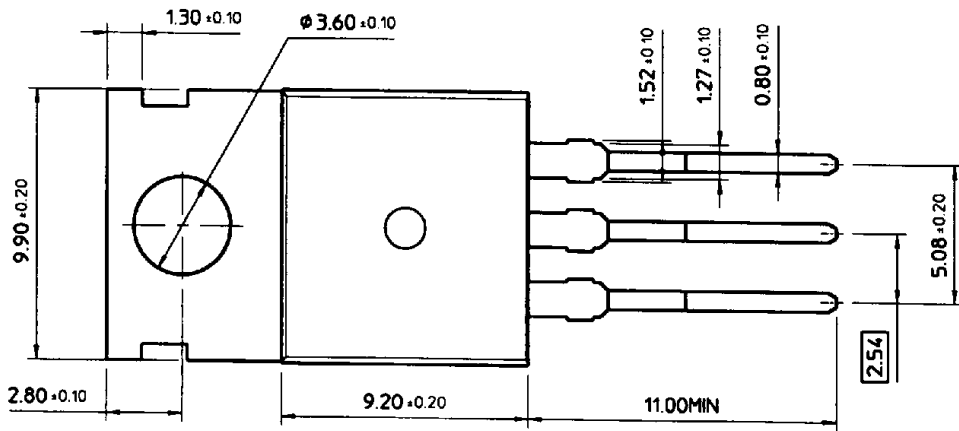
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NOTE